

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4440680	substrate carrier board pcb wcb ((printed wiring circuit circuitry multilayer multi) adj4 board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:07
L2	1355987	board pcb wcb ((printed wiring circuit circuitry multilayer multi) adj4 board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:07
L3	1744202	(upper lower top bottom first second) with (semiconductor dice chip die ic (integrated adj circuit) electronic component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:10
L4	89219	2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:12
L5	61473	2 with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:13
L6	10199	(bga bump ball flipchip (flip adj chip)) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:13
L7	6548	5 same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:14
L8	933	7 and (mother motherboard)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 16:14